
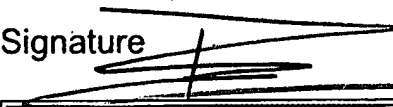


## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18  
Stylesheet Version v18.0

Title of Invention	Aluminum Pad Power Bus and Signal Routing for Integrated Circuit Devices Utilizing Copper Technology Interconnect Structures																								
Application Number: 10/675258 																									
Confirmation Number: 4017																									
First Named Applicant: Seung Kang																									
Attorney Docket Number: 075903-218																									
Art Unit: 2816																									
Search string: ( 5148263 or 6225207 ).pn.																									
US Patent Documents																									
Note: Applicant is not required to submit a paper copy of cited US Patent Documents																									
<table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td>TL</td><td>1</td><td>5148263</td><td>1992-09-15</td><td>Hamai</td><td></td><td></td><td></td></tr><tr><td>TL</td><td>2</td><td>6225207</td><td>2001-05-01</td><td>Parikh</td><td></td><td></td><td></td></tr></tbody></table>		init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass	TL	1	5148263	1992-09-15	Hamai				TL	2	6225207	2001-05-01	Parikh			
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